



**ALPHA & OMEGA**  
SEMICONDUCTOR

**AOD6N50**

**500V, 5.3A N-Channel MOSFET**

### General Description

The AOD6N50 is fabricated using an advanced high voltage MOSFET process that is designed to deliver high levels of performance and robustness in popular AC-DC applications. By providing low  $R_{DS(on)}$ ,  $C_{iss}$  and  $C_{rss}$  along with guaranteed avalanche capability this device can be adopted quickly into new and existing offline power supply designs.

### Product Summary

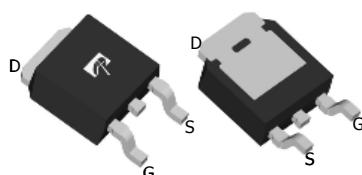
$V_{DS}$	600V@150°C
$I_D$ (at $V_{GS}=10V$ )	5.3A
$R_{DS(ON)}$ (at $V_{GS}=10V$ )	< 1.4Ω

100% UIS Tested!  
100%  $R_g$  Tested!

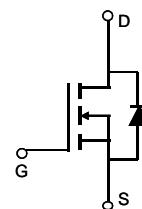


**TO252  
DPAK**

Top View



Bottom View



### Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	$V_{DS}$	500	V
Gate-Source Voltage	$V_{GS}$	$\pm 30$	V
Continuous Drain Current <sup>B</sup>	$I_D$	5.3	A
$T_C=100^\circ\text{C}$		3.3	
Pulsed Drain Current <sup>C</sup>	$I_{DM}$	17	
Avalanche Current <sup>C</sup>	$I_{AR}$	2.8	A
Repetitive avalanche energy <sup>C</sup>	$E_{AR}$	118	mJ
Single pulsed avalanche energy <sup>H</sup>	$E_{AS}$	235	mJ
Peak diode recovery dv/dt	dv/dt	5	V/ns
Power Dissipation <sup>B</sup>	$P_D$	104	W
$T_C=25^\circ\text{C}$		0.83	W/ °C
Junction and Storage Temperature Range	$T_J, T_{STG}$	-50 to 150	°C
Maximum lead temperature for soldering purpose, 1/8" from case for 5 seconds	$T_L$	300	°C

### Thermal Characteristics

Parameter	Symbol	Typical	Maximum	Units
Maximum Junction-to-Ambient <sup>A,G</sup>	$R_{\theta JA}$	43	55	°C/W
Maximum Case-to-sink <sup>A</sup>	$R_{\theta CS}$	-	0.5	°C/W
Maximum Junction-to-Case <sup>D,F</sup>	$R_{\theta JC}$	1	1.2	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>STATIC PARAMETERS</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$I_D=250\mu\text{A}, V_{GS}=0\text{V}, T_J=25^\circ\text{C}$	500			V
		$I_D=250\mu\text{A}, V_{GS}=0\text{V}, T_J=150^\circ\text{C}$		600		
$BV_{DSS}/\Delta T_J$	Zero Gate Voltage Drain Current	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$		0.6		$\text{V}/^\circ\text{C}$
		$V_{DS}=500\text{V}, V_{GS}=0\text{V}$			1	
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=400\text{V}, T_J=125^\circ\text{C}$			10	$\mu\text{A}$
		$V_{DS}=0\text{V}, V_{GS}=\pm 30\text{V}$			$\pm 100$	
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=5\text{V} I_D=250\mu\text{A}$	3.4	4.1	4.5	V
$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}, I_D=2.5\text{A}$		1.2	1.4	$\Omega$
$g_{FS}$	Forward Transconductance	$V_{DS}=40\text{V}, I_D=2.5\text{A}$		5		S
$V_{SD}$	Diode Forward Voltage	$I_S=1\text{A}, V_{GS}=0\text{V}$		0.76	1	V
$I_S$	Maximum Body-Diode Continuous Current			5		A
$I_{SM}$	Maximum Body-Diode Pulsed Current			17		A
<b>DYNAMIC PARAMETERS</b>						
$C_{iss}$	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=25\text{V}, f=1\text{MHz}$	430	538	670	pF
$C_{oss}$	Output Capacitance		40	58	80	pF
$C_{rss}$	Reverse Transfer Capacitance		2.5	4.5	7	pF
$R_g$	Gate resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$	1.2	2.3	3.5	$\Omega$
<b>SWITCHING PARAMETERS</b>						
$Q_g$	Total Gate Charge	$V_{GS}=10\text{V}, V_{DS}=400\text{V}, I_D=5\text{A}$	9	11.5	14	nC
$Q_{gs}$	Gate Source Charge		3	3.8	4.6	nC
$Q_{gd}$	Gate Drain Charge		2	4.1	6.2	nC
$t_{D(\text{on})}$	Turn-On Delay Time	$V_{GS}=10\text{V}, V_{DS}=250\text{V}, I_D=5\text{A}, R_G=25\Omega$		18		ns
$t_r$	Turn-On Rise Time			32		ns
$t_{D(\text{off})}$	Turn-Off Delay Time			34		ns
$t_f$	Turn-Off Fall Time			22		ns
$t_{rr}$	Body Diode Reverse Recovery Time	$I_F=5\text{A}, dI/dt=100\text{A}/\mu\text{s}, V_{DS}=100\text{V}$	145	182	220	ns
$Q_{rr}$	Body Diode Reverse Recovery Charge	$I_F=5\text{A}, dI/dt=100\text{A}/\mu\text{s}, V_{DS}=100\text{V}$	1.7	2.2	2.7	$\mu\text{C}$

- A. The value of  $R_{\text{BJA}}$  is measured with the device in a still air environment with  $T_A=25^\circ\text{C}$ .  
B. The power dissipation  $P_D$  is based on  $T_{J(\text{MAX})}=150^\circ\text{C}$  in a TO252 package, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.  
C. Repetitive rating, pulse width limited by junction temperature  $T_{J(\text{MAX})}=150^\circ\text{C}$ .  
D. The  $R_{\text{BJA}}$  is the sum of the thermal impedance from junction to case  $R_{\text{BJC}}$  and case to ambient.  
E. The static characteristics in Figures 1 to 6 are obtained using  $<300\ \mu\text{s}$  pulses, duty cycle 0.5% max.  
F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of  $T_{J(\text{MAX})}=150^\circ\text{C}$ .  
G. These tests are performed with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ\text{C}$ .  
H.  $L=60\text{mH}, I_{AS}=2.8\text{A}, V_{DD}=150\text{V}, R_G=10\Omega$ , Starting  $T_J=25^\circ\text{C}$

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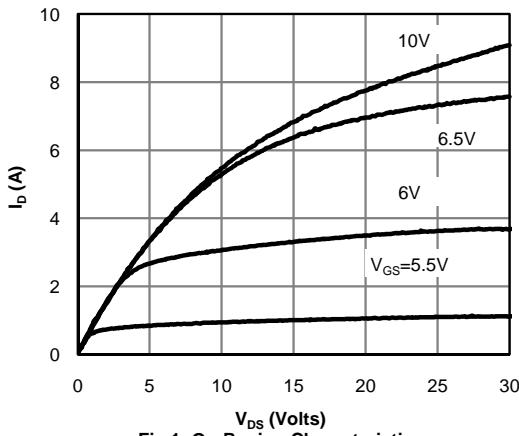
**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**


Fig 1: On-Region Characteristics

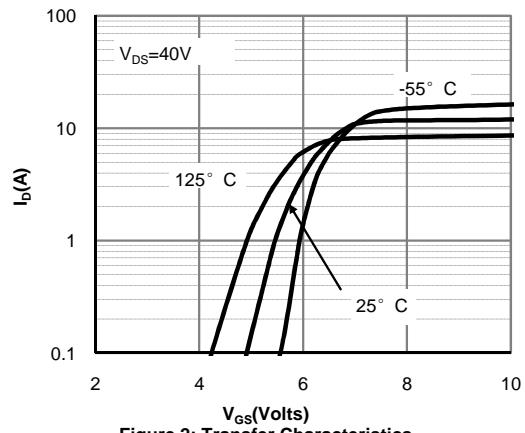


Figure 2: Transfer Characteristics

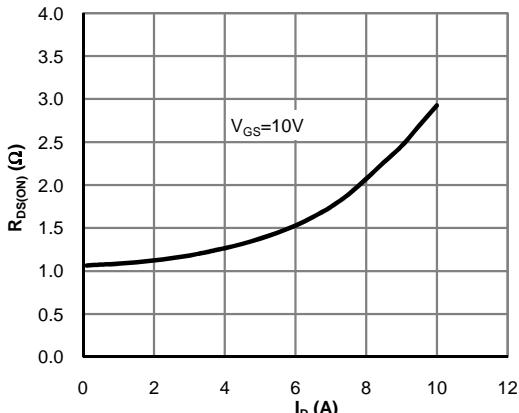


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

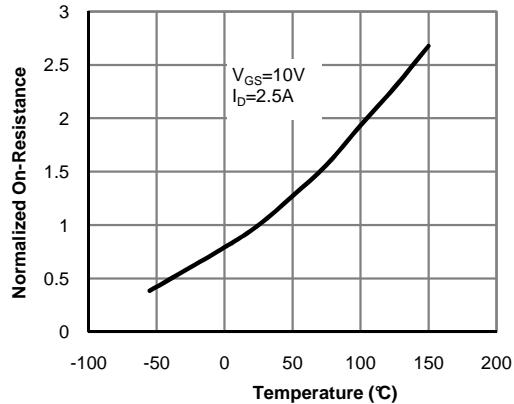


Figure 4: On-Resistance vs. Junction Temperature

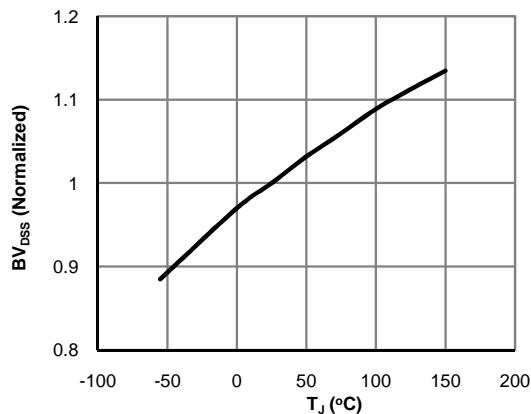


Figure 5: Break Down vs. Junction Temperature

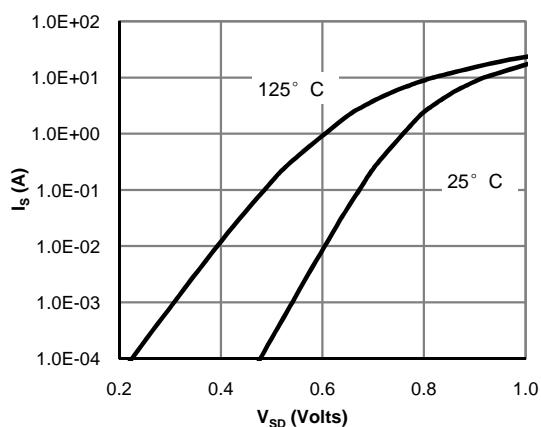


Figure 6: Body-Diode Characteristics

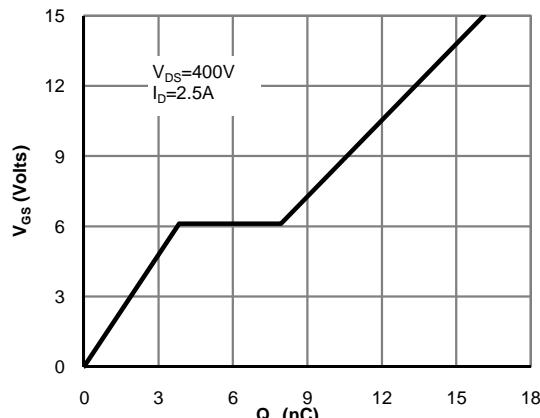
**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**


Figure 7: Gate-Charge Characteristics

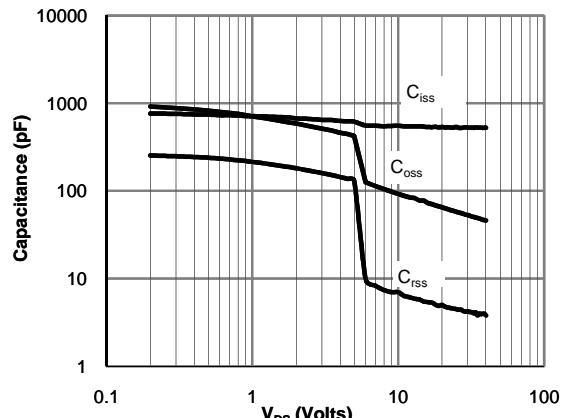


Figure 8: Capacitance Characteristics

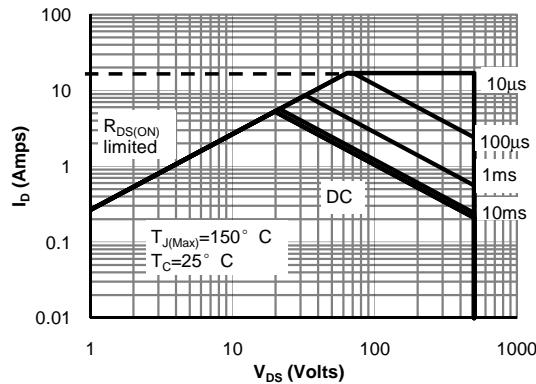


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

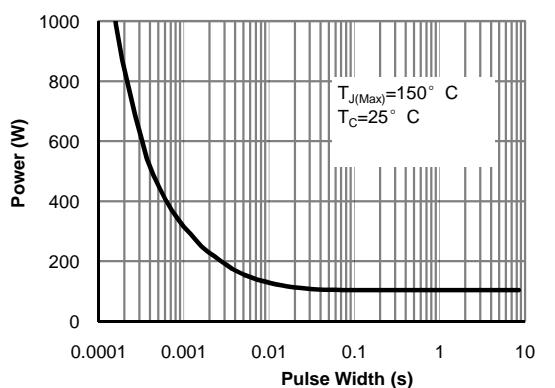


Figure 10: Single Pulse Power Rating Junction-to-Case (Note F)

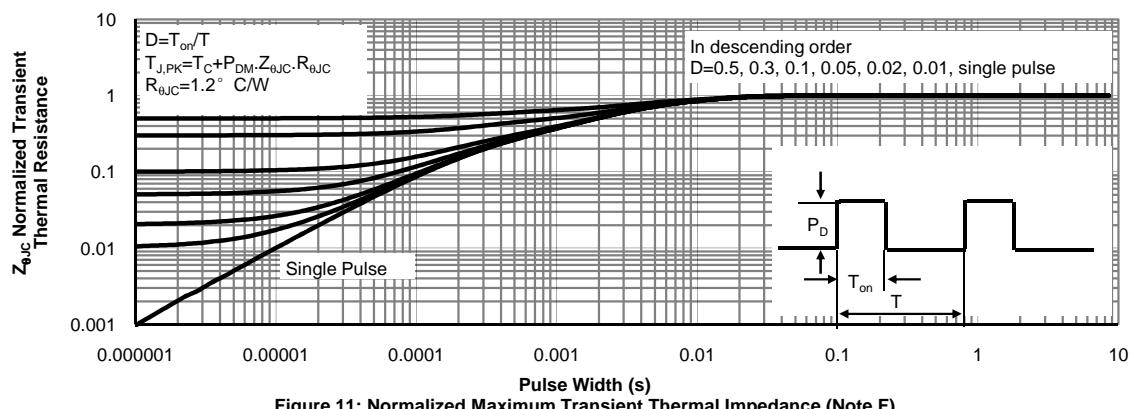


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

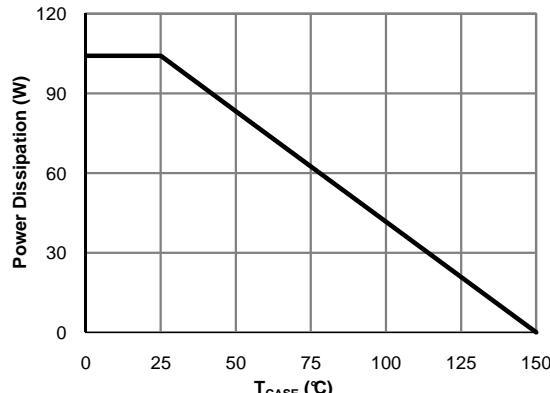
**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**


Figure 12: Power De-rating (Note B)

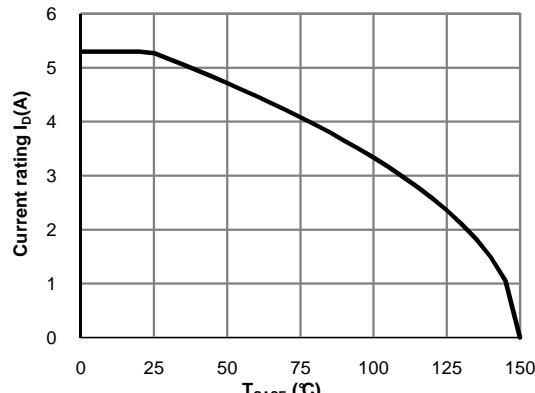


Figure 13: Current De-rating (Note B)

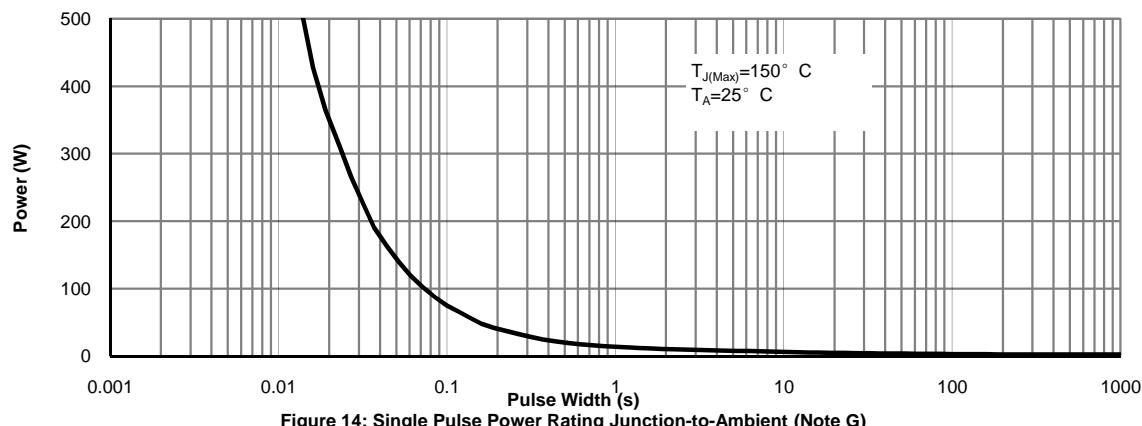


Figure 14: Single Pulse Power Rating Junction-to-Ambient (Note G)

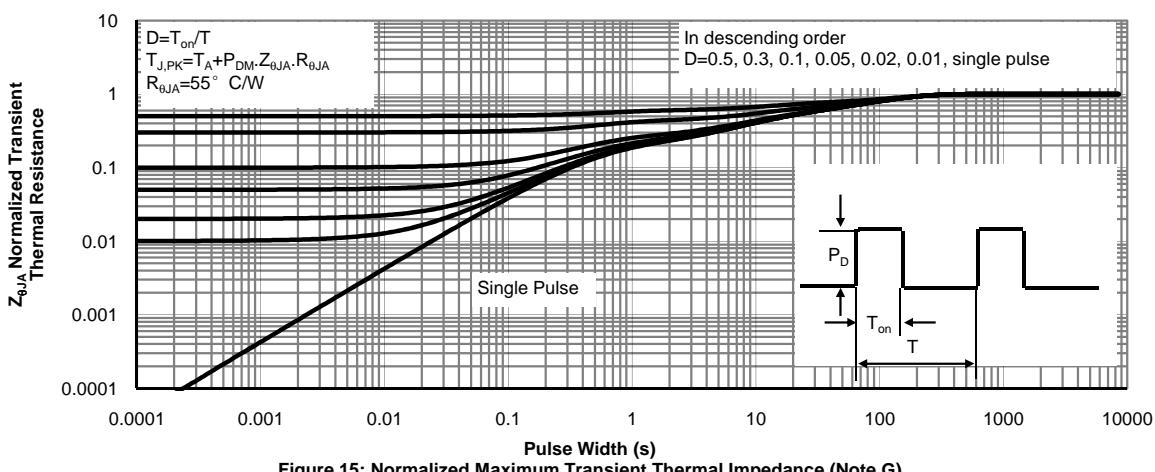
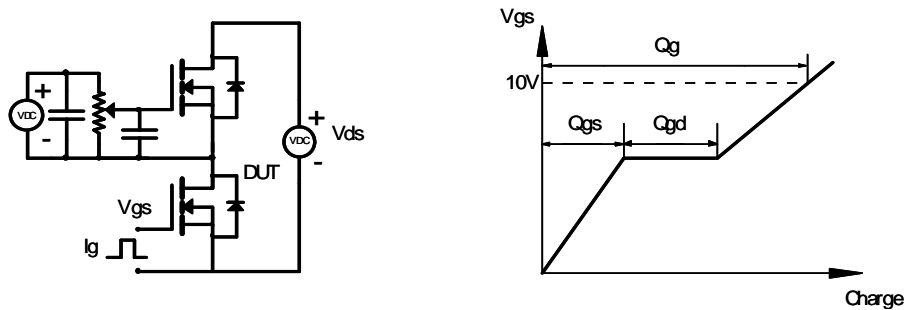
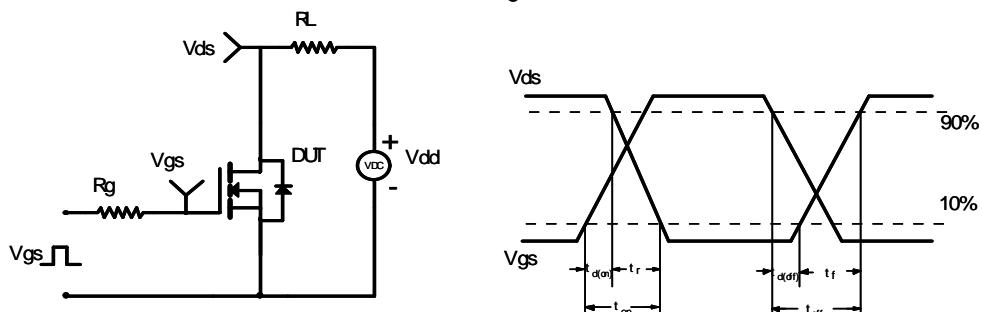


Figure 15: Normalized Maximum Transient Thermal Impedance (Note G)

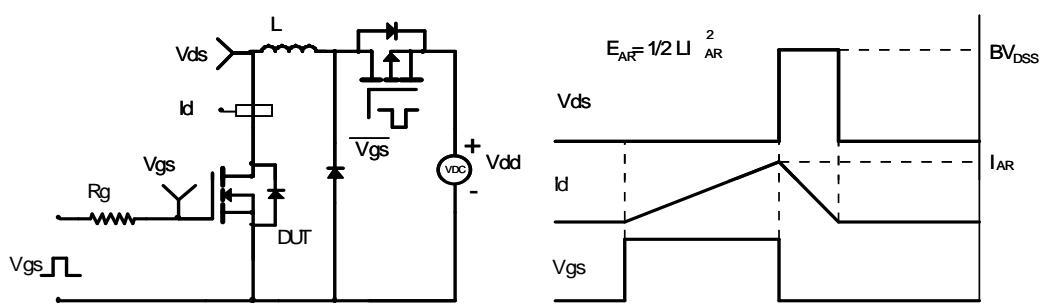
Gate Charge Test Circuit &amp; Waveform



Resistive Switching Test Circuit &amp; Waveforms



Unclamped Inductive Switching (UIS) Test Circuit &amp; Waveforms



Diode Recovery Test Circuit &amp; Waveforms

